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5380635-2 Product Details

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5380635-2

TE Internal Number: 5380635-2

Active

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Discrete Sockets



Always EU RoHS/ELV Compliant (Statement of Compliance)

Product Highlights:

- Mini-Spring Socket Product Line
- Board-to-Board, Wire-to-Board
- Applies To Wire/Cable, Applies To Printed Circuit Board
- Contact - Rated Current = 7.5 A
- Wire/Cable Size = .162 - .653 mm²

[View all Features](#)

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Documentation & Additional Information

Product Drawings:

- [REUSABLE COMPONENT RECEPTACLE](#) (PDF, English)

Catalog Pages/Data Sheets:

- None Available

Product Specifications:

- None Available

Application Specifications:

- None Available

Instruction Sheets:

- None Available

CAD Files: (CAD Format & Compression Information)

- [2D Drawing](#) (DXF, Version A)
- [3D Model](#) (IGES, Version A)
- [3D Model](#) (STEP, Version A)

Additional Information:

- [Product Line Information](#)

Related Products:

- [Tooling](#)

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Product Features (Please use the Product Drawing for all design activity)

Product Type Features:

- Product Line = Mini-Spring Socket
- [Socket Length \(mm \[in\]\)](#) = 6.45 [0.254]
- [Sleeve Style](#) = Open Bottom
- [Sealant](#) = Without
- Wire/Cable Type = Discrete Wire
- Termination Method to Wire/Cable = Solder
- Termination Method to PC Board = Through Hole - Press Fit
- Product Series = 5
- Sleeve Material = Copper
- Profile = Zero

Electrical Characteristics:

- Contact - Rated Current (A) = 7.5

Termination Features:

- Wire/Cable Size (mm²) = 0.162 - 0.653
- Wire/Cable Size (AWG) = 19 - 25
- [Insertion Method](#) = Hand/Semi-Automatic

Dimensions:

- Recommended Hole Size (mm [in]) = 2.26 [0.089]
- PCB Thickness, Recommended (mm [in]) = 0.79 - 3.18 [0.031 - 0.125]

Body Features:

- [Mating Pin Dia. Range \(mm \[in\]\)](#) = 0.46 - 1.02 [0.018 - 0.040]
- [Sleeve Material Plating](#) = Tin
- Wire Type = Solid
- Spring Material = Beryllium Copper

Contact Features:

- [Contact Spring Plating](#) = Gold (30)
- Contact Plating, Mating Area, Material = Gold (30)
- Contact Plating, Mating Area, Thickness (µm [µin]) = 0.00076 [0.03]
- Contact Type = Socket
- Contact Base Material = Beryllium Copper

Industry Standards:

- Government/Industry Qualification = No
- [RoHS/ELV Compliance](#) = RoHS compliant, ELV compliant
- [Lead Free Solder Processes](#) = Wave solder capable to 240°C, Wave solder capable to 260°C, Wave solder capable to 265°C, Reflow solder capable to 245°C, Reflow solder capable to 260°C, Pin-in-Paste capable to 245°C, Pin-in-Paste capable to 260°C
- RoHS/ELV Compliance History = Always was RoHS compliant

Environmental:

- Operating Temperature (°C [°F]) = -65 - +126 [-85 - +258]

Conditions for Usage:

- Applies To = Wire/Cable, Printed Circuit Board

Operation/Application:

- Application Use = Board-to-Board, Wire-to-Board
- Contact Transmits (Typical Application) = Signal (Data)/Power
- Application = Testing/Reusable

Packaging Features:

- Packaging Method = Loose Piece
- Packaging Quantity = 2,000/Bag

Other:

- Brand = AMP

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